

## 1. Product profile

### 1.1 General description

Ultrafast, dual common cathode, epitaxial rectifier diode in a SOT226 (I2PAK), low-profile plastic package.

### 1.2 Features

- Fast switching
- Soft recovery characteristic
- Low switching loss
- Low thermal resistance
- High thermal cycling performance
- Low forward voltage drop

### 1.3 Applications

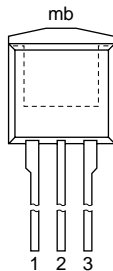
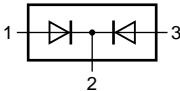
- Output rectifiers in high frequency switched-mode power supplies
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

### 1.4 Quick reference data

- $V_{RRM} \leq 600 \text{ V}$
- $V_F \leq 1.16 \text{ V}$
- $I_{O(AV)} \leq 20 \text{ A}$
- $t_{rr} \leq 60 \text{ ns}$

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode 1		 sym084
2	cathode		
3	anode 2		
mb	mounting base; cathode		

SOT226 (I2PAK)

### 3. Ordering information

**Table 2. Ordering information**

Type number	Package		Version
	Name	Description	
BYV34G-600	I2PAK	plastic single-ended package (I2PAK); low-profile 3-lead TO-220AB	SOT226B

### 4. Limiting values

**Table 3. Limiting values**

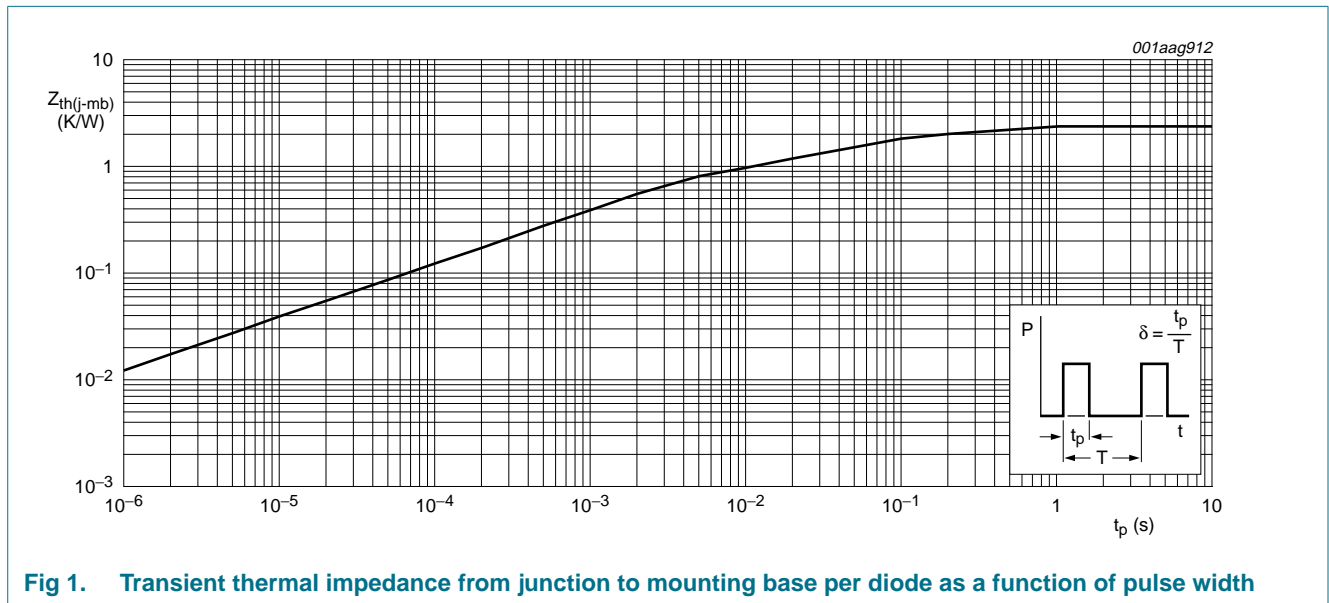
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	DC; $T_{mb} \leq 138\text{ °C}$	-	600	V
$I_{O(AV)}$	average output current	square waveform; $\delta = 0.5$ ; $T_{mb} \leq 107\text{ °C}$ ; both diodes conducting	-	20	A
$I_{FRM}$	repetitive peak forward current	$t_p = 25\ \mu\text{s}$ square waveform; $\delta = 0.5$ ; $T_{mb} \leq 107\text{ °C}$ ; per diode	-	20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; sinusoidal waveform; per diode	-	120	A
		$t_p = 8.3\text{ ms}$ ; sinusoidal waveform; per diode	-	132	A
$T_{stg}$	storage temperature		-40	+150	°C
$T_j$	junction temperature		-	150	°C

### 5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound per diode; see <a href="#">Figure 1</a>	-	-	2.4	K/W
		with heatsink compound; both diodes conducting	-	-	1.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

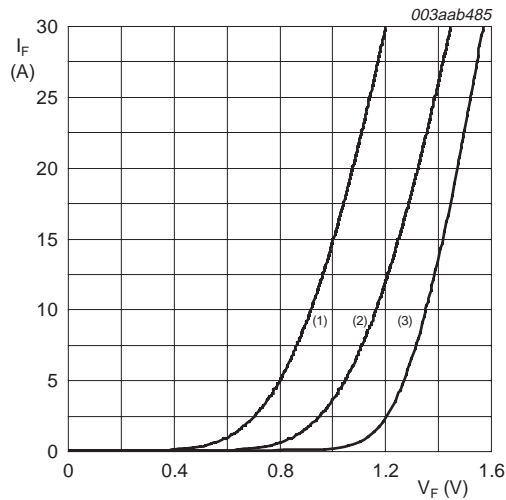


## 6. Characteristics

**Table 5. Characteristics**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}; T_j = 150\text{ }^\circ\text{C};$ see <a href="#">Figure 2</a>	-	0.92	1.16	V
		$I_F = 20\text{ A}$	-	1.07	1.48	V
$I_R$	reverse current	$V_R = 600\text{ V}$	-	10	50	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 100\text{ }^\circ\text{C}$	-	0.2	0.6	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 2\text{ A to } V_R = 30\text{ V}; dI_F/dt = 20\text{ A}/\mu\text{s};$ see <a href="#">Figure 3</a>	-	40	70	nC
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A to } V_R = 30\text{ V}; dI_F/dt = 100\text{ A}/\mu\text{s};$ ramp recovery; see <a href="#">Figure 3</a>	-	50	60	ns
$I_{RM}$	peak reverse recovery current	$I_F = 10\text{ A to } V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C};$ see <a href="#">Figure 3</a>	-	3	5	A
$V_{FR}$	forward recovery voltage	$I_F = 10\text{ A}; dI_F/dt = 10\text{ A}/\mu\text{s};$ see <a href="#">Figure 4</a>	-	3.2	-	V



- (1)  $T_j = 150\text{ }^\circ\text{C};$  typical values
- (2)  $T_j = 150\text{ }^\circ\text{C};$  maximum values
- (3)  $T_j = 25\text{ }^\circ\text{C};$  maximum values

**Fig 2. Forward current as a function of forward voltage**

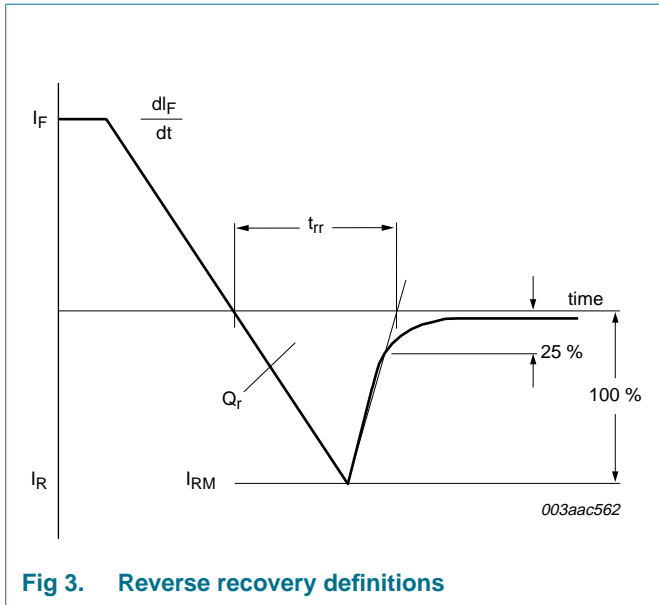


Fig 3. Reverse recovery definitions

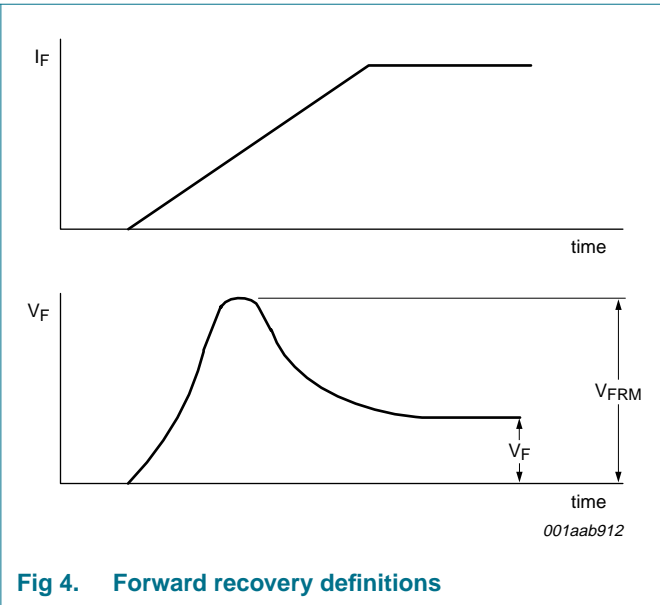


Fig 4. Forward recovery definitions

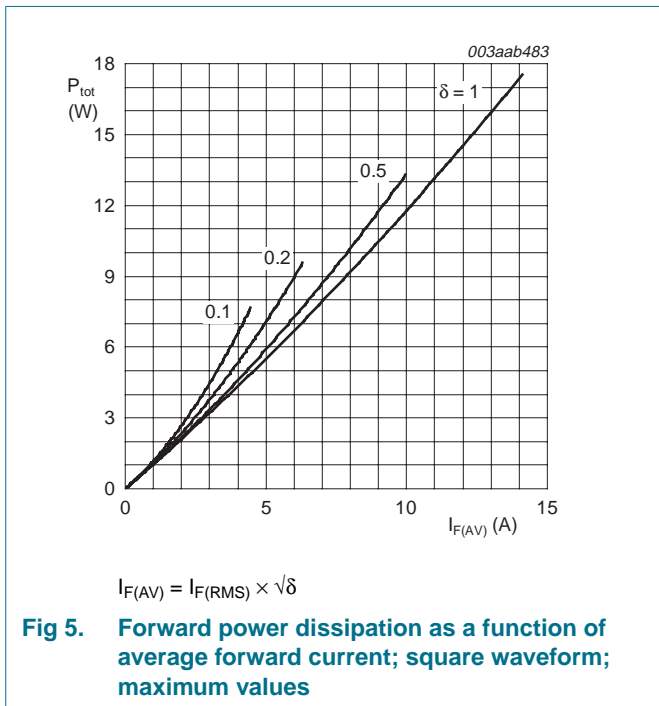


Fig 5. Forward power dissipation as a function of average forward current; square waveform; maximum values

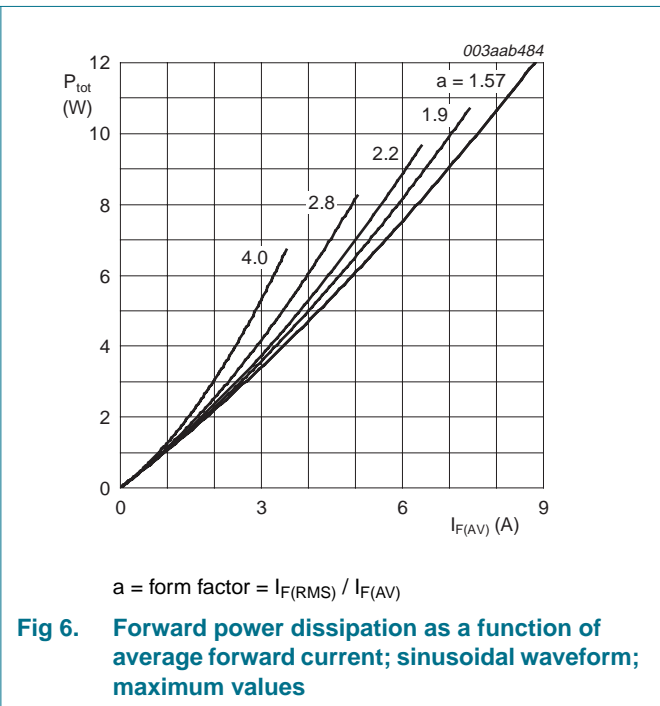
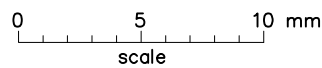
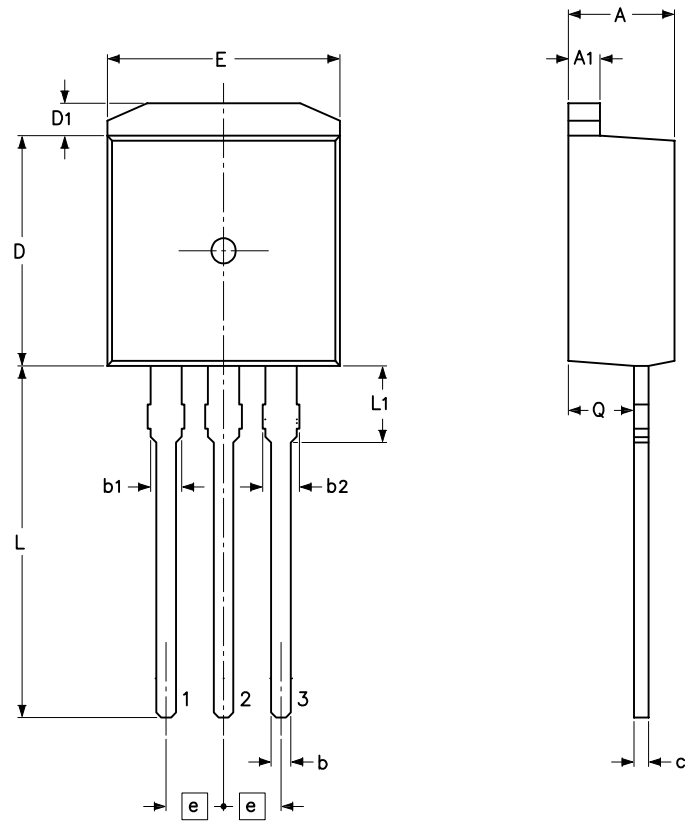


Fig 6. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

### 7. Package outline

Plastic single-ended package (I2PAK); low-profile 3-lead TO-262

SOT226B



Dimensions

Unit	A	A1	b	b1	b2	c	D	D1	E	e	L	L1	Q
max	4.7	1.40	0.85	1.40	1.7	0.65	9.4	1.32	10.30	2.54	15.0	3.30	2.6
nom										(REF)			
min	4.3	1.15	0.60	1.14	1.3	0.45	8.6	1.02	9.65		12.5	2.79	2.2

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT226B		TO-262				16-10-17

Fig. 1. Package outline I2PAK (SOT226B)

## 8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYV34G-600_1	20090225	Product data sheet	-	-

## 9. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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